

TOSHIBA PHOTO-IC Si MONOLITHIC PHOTO-IC

# TPS831

HIGH-SPEED OPTICAL REMOTE CONTROLLERS

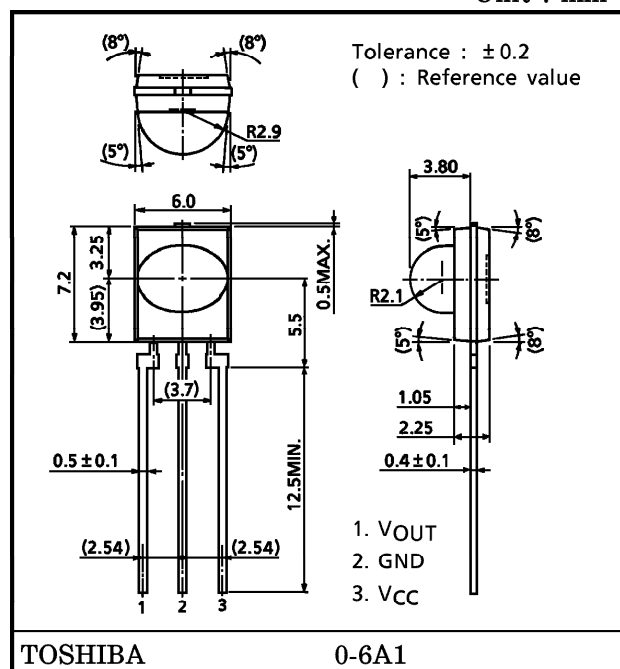
CORDLESS CONTROLLERS FOR VIDEOGAMES

ELECTRONIC ORGANIZERS AND OTHER NEW  
PORTABLE INFORMATION DEVICES

IR DATA COMMUNICATIONS

- Photodiode, I-V converter, band-pass filter and AGC amplifier all incorporated in a single chip
- Carrier frequency :  $f_0 = 455 \text{ kHz}$  (typ.)
- Supply voltage :  $V_{CC} = 5 \text{ V}$
- Visible light cut-off frequency :  $800 \text{ nm}$
- TLN105B and TLN115A available as infrared LEDs for remote controllers

Unit : mm



Weight : 0.3 g (typ.)

MAXIMUM RATINGS ( $T_a = 25^\circ\text{C}$ )

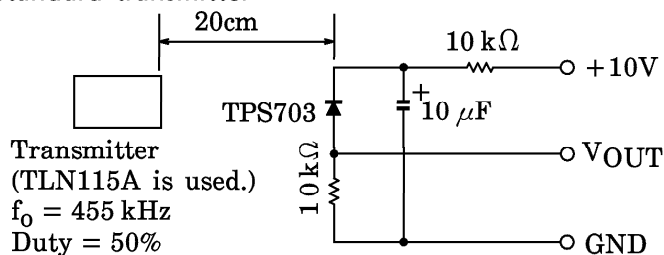
CHARACTERISTIC	SYMBOL	RATING	UNIT
Supply Voltage	$V_{CC}$	7	V
Operating Temperature Range	$T_{opr}$	$-20 \sim 60$	$^\circ\text{C}$
Storage Temperature Range	$T_{stg}$	$-30 \sim 100$	$^\circ\text{C}$
Soldering Temperature Range (5s)	$T_{sol}$	260	$^\circ\text{C}$

OPTICAL AND ELECTRICAL CHARACTERISTICS ( $V_{CC} = 5\text{ V}$ ,  $T_a = 25^\circ\text{C}$ ,  $C = 1000\text{ pF}$  : Note 1)

CHARACTERISTIC	SYMBOL	TEST CONDITION	Min	Typ.	Max	UNIT
Supply Voltage	$V_{CC}$	—	3	5	7	V
Supply Current	$I_{CC}$	$E = 0$	—	1.2	3.0	mA
Electromagnetic Sensitivity	$E_S$	(Note 5)	—	250	—	$V_{p-p}/m$
Transmission Range	$L$ (Note 3)	The burst wave shown in Note 4 is transmitted by a standard transmitter (Note 2).	3	5	—	m
High-Level Output Voltage	$V_{OH}$	External light intensity $< 500\text{ lx}$ Output Current $< 10\text{ }\mu\text{A}$	4.0	—	—	V
Low-Level Output Voltage	$V_{OL}$		—	—	0.5	V
ON Pulse Width	$T_{ON}$	External light intensity $< 500\text{ lx}$ Output Current $< 10\text{ }\mu\text{A}$	16	25	40	$\mu\text{s}$
OFF Pulse Width	$T_{OFF}$		—	63	—	$\mu\text{s}$
Carrier Frequency	$f_o$	—	—	455	—	kHz
Radiation Angle	$\theta_H$	Horizontal angle, $L/2$ (Note 6)	$\pm 55$	$\pm 63$	—	$^\circ$
	$\theta_V$	Vertical angle, $L/2$ (Note 6)	$\pm 25$	$\pm 30$	—	$^\circ$

(Note 1) : Measurements for the TPS831 are based on a standard circuit which includes a 1000-pF capacitor between  $V_O$  and GND to prevent oscillation.

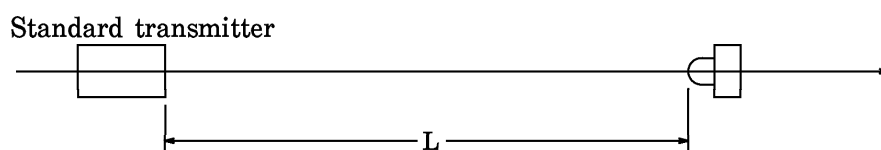
(Note 2) : Standard transmitter



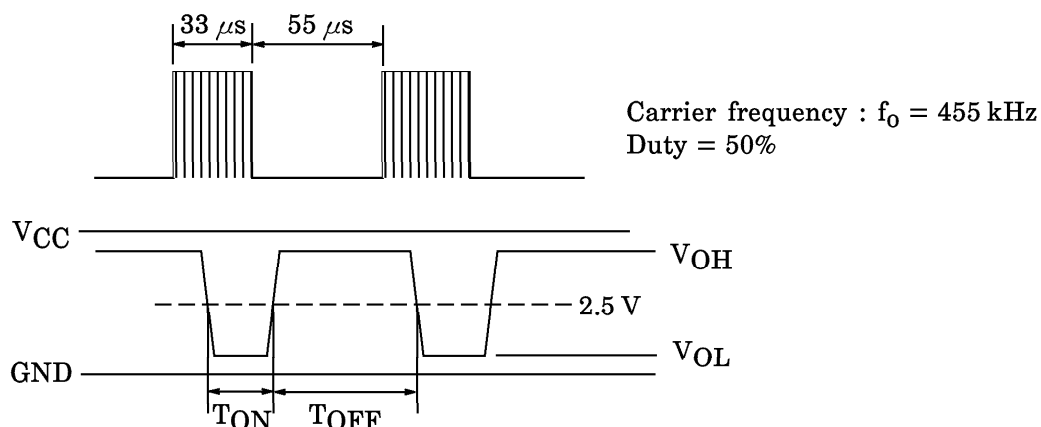
In the figure above, the transmitter output  $V_{OUT}$  is 80 mVpp.

The TPS703 in this application has a short-circuit current of  $I_{SC} = 1.24\text{ }\mu\text{A}$  when measured at  $E = 0.1\text{ mW}/\text{cm}^2$ . ( $E$  is the radiant incidence when a CIE standard light source A is used.)

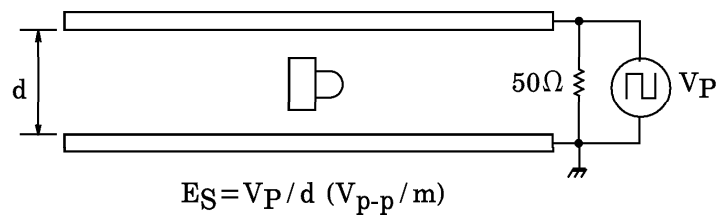
(Note 3) : Transmission range  $L$



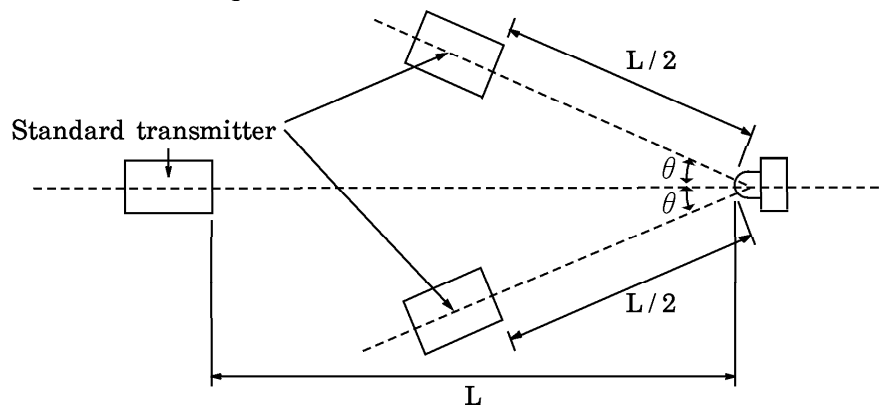
(Note 4) Burst wave



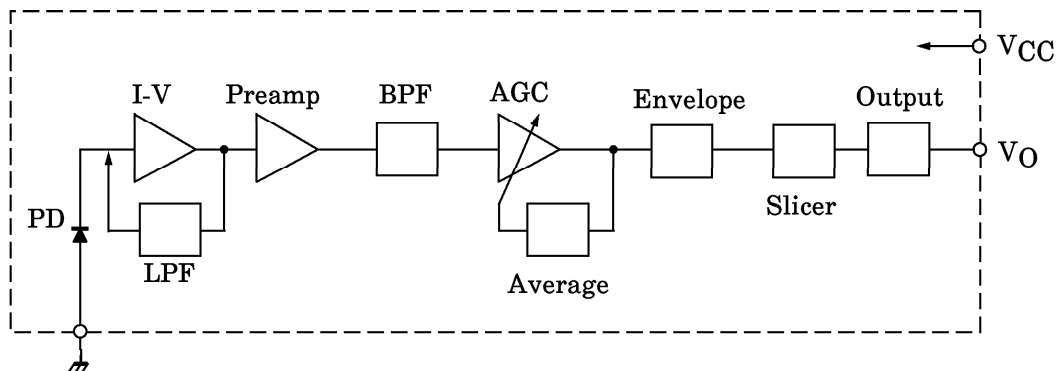
(Note 5) : Electromagnetic sensitivity



(Note 6) : Radiation angle



Circuit block diagram



### Bit pattern designing example (reference)

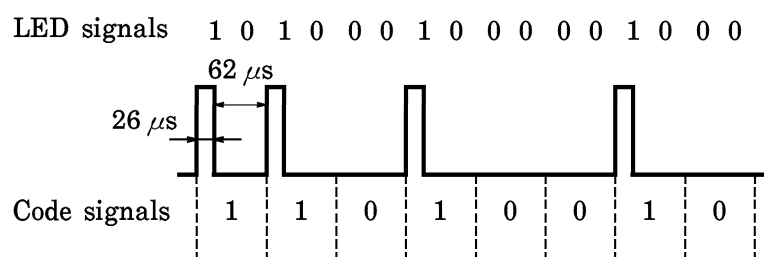
- Example of code signal = 11010010

Sequence of LED signals = 1 must be avoided. If LED signals of 1 sequence, TPS830 may not receive LED signals properly. After an LED signal of 1, 0 must be sent (55  $\mu$ s or longer interval necessary). Please take this into account when designing a bit pattern. The following shows the bit pattern example that is converted at first code signals to LED signals as shown on the right diagram.

#### <Conversion example>

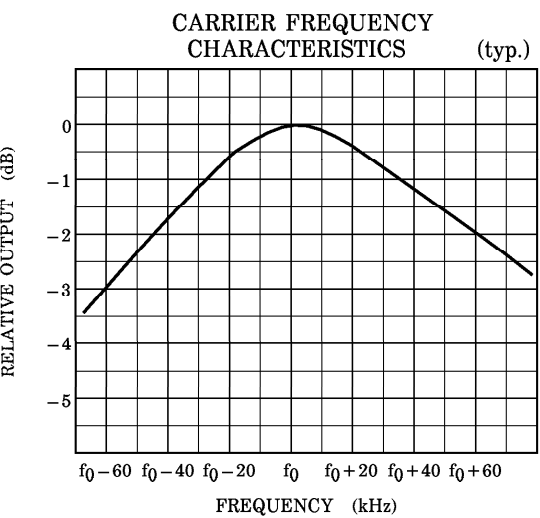
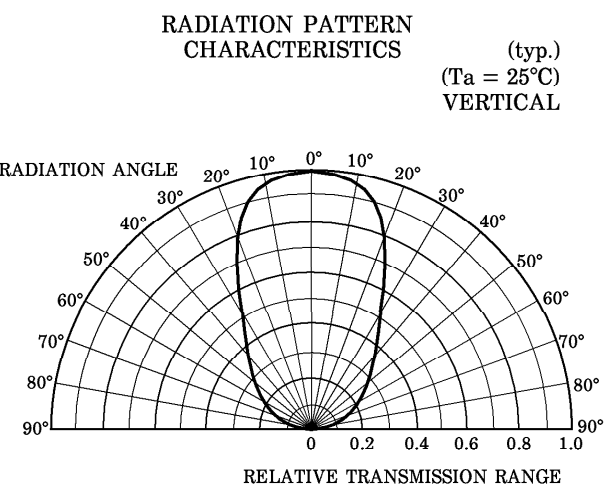
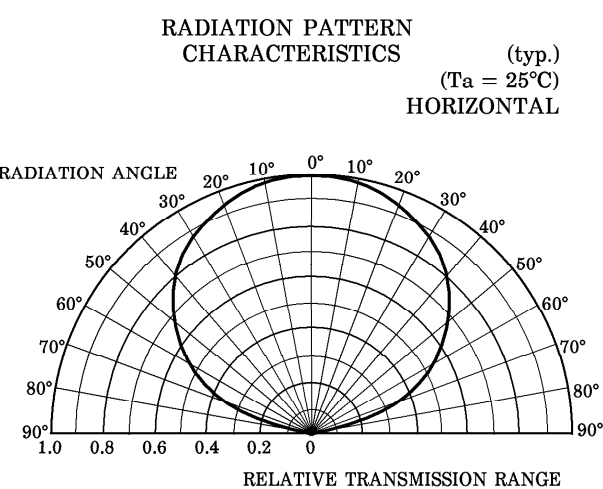
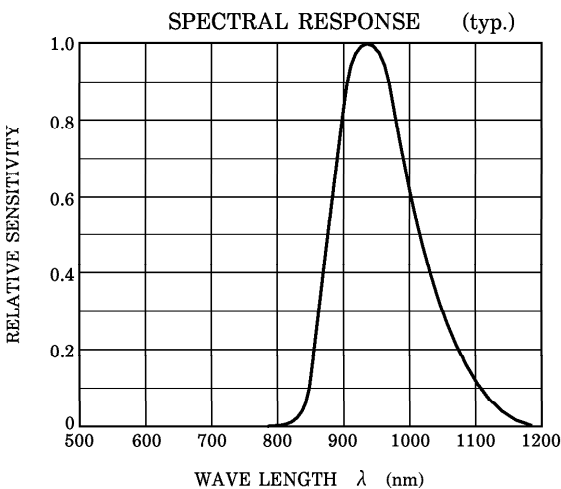
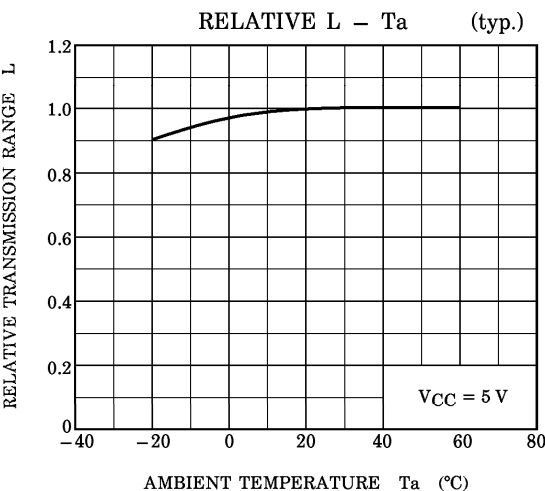
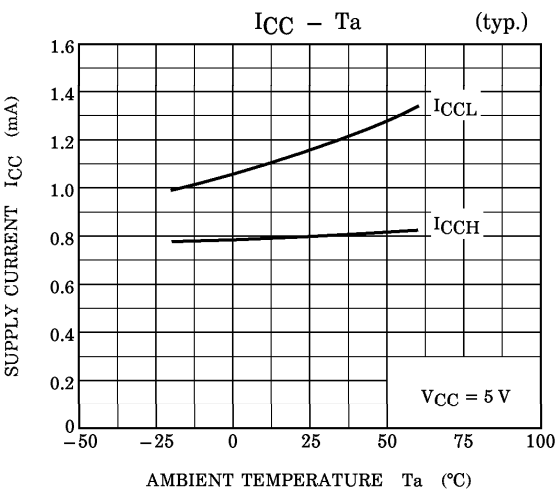
Code signal	LED signal
0	→ 00
1	→ 10

#### <Pattern example>



### PRECAUTIONS

1. To stabilize the power line, insert a bypass capacitor of up to 0.01  $\mu$ F between  $V_{CC}$  and GND, close to the device.
2. At power-on the internal circuit takes about 100  $\mu$ s to stabilize. During this period the output signal is unstable and may change.
3. To avoid unnecessary oscillation, insert a bypass capacitor of 1000 pF between  $V_{CC}$  and GND.
4. When using the device, please take the device's characteristics, the operating environment and the characteristics of pairing LED device into considerations.
5. Soldering temperature :  $\leq 260^{\circ}\text{C}$ , Soldering time :  $\leq 5$  s (Soldering must be performed under the 2 mm from the body of the device.)
6. When forming the leads, bend each lead under the 2 mm from the body of the device. Soldering must be performed after the leads have been formed.



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